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1 Block diagrams and pins configurations

Figure 1. VNL5160N3-E block diagram

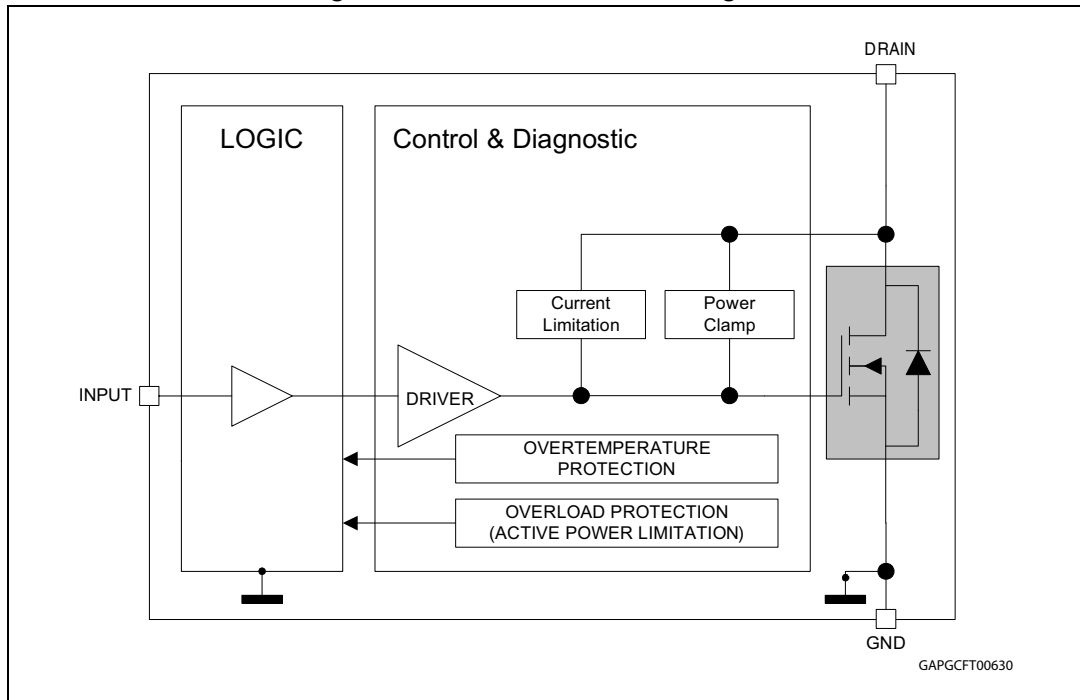


Figure 2. VNL5160S5-E block diagram

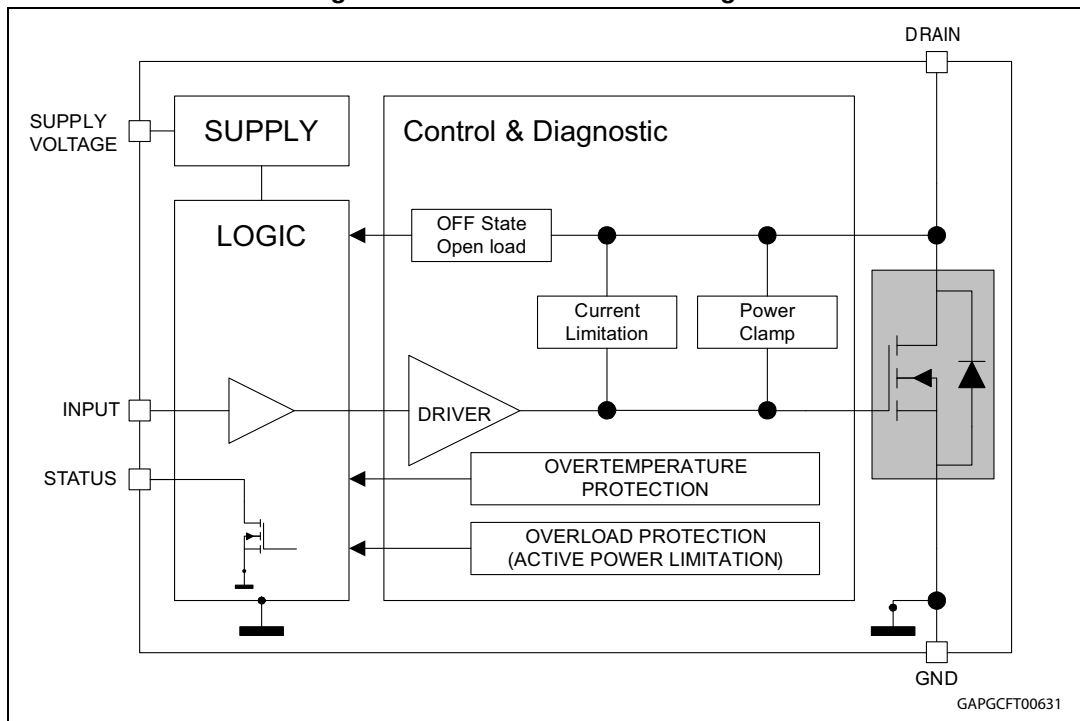


Table 2. Pin function

Name	Function
INPUT	Voltage controlled input pin with hysteresis, CMOS compatible. Controls output switch state ⁽¹⁾
DRAIN	PowerMOS drain
SOURCE	PowerMOS source and ground reference for the control section
SUPPLY VOLTAGE	Supply voltage connected to the signal part (5V)
STATUS	Open drain digital diagnostic pin ⁽²⁾

- 1. Internally connected to V_{supply} in the VNL5160N3-E.
- 2. Valid for VNL5160S5-E only.

Figure 3. VNL5160N3-E current and voltage conventions

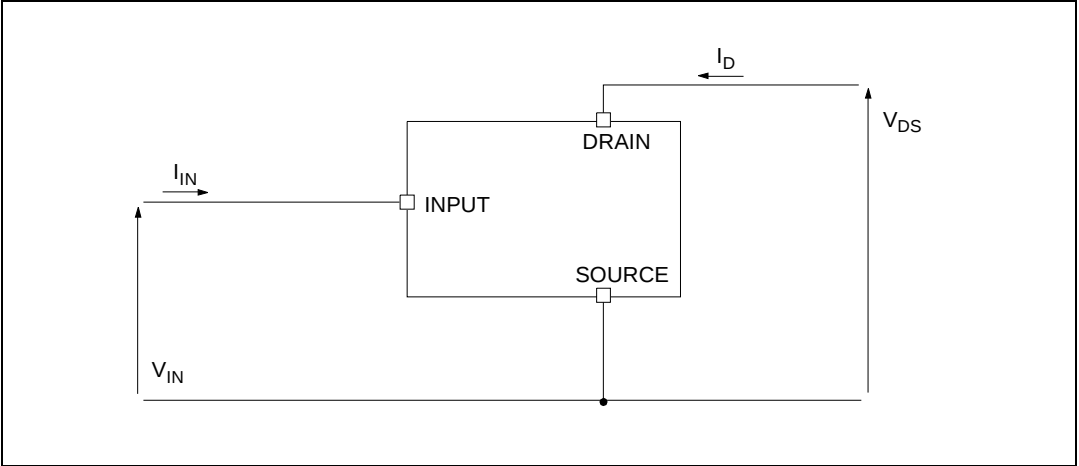


Figure 4. VNL5160S5-E current and voltage conventions

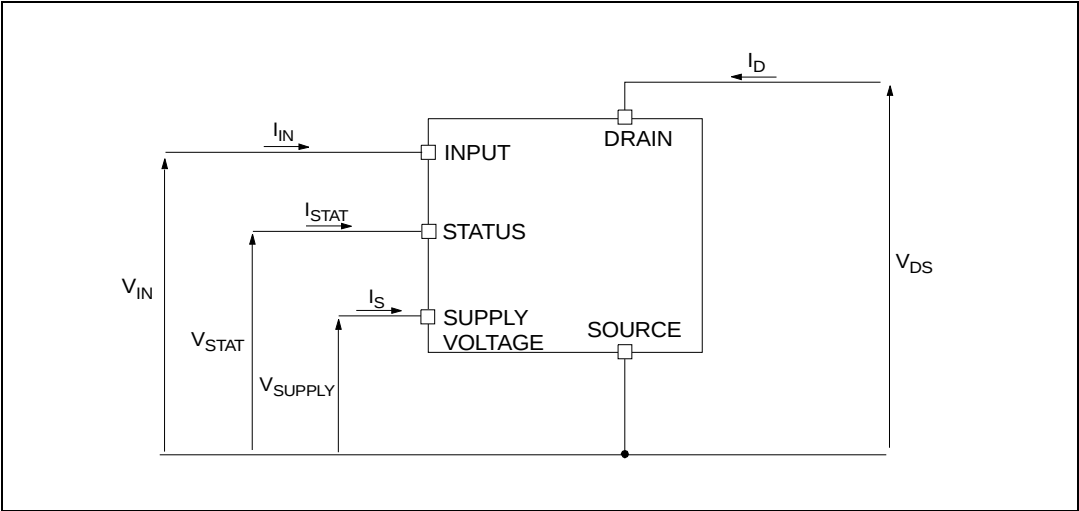


Figure 5. Configuration diagrams (top view)

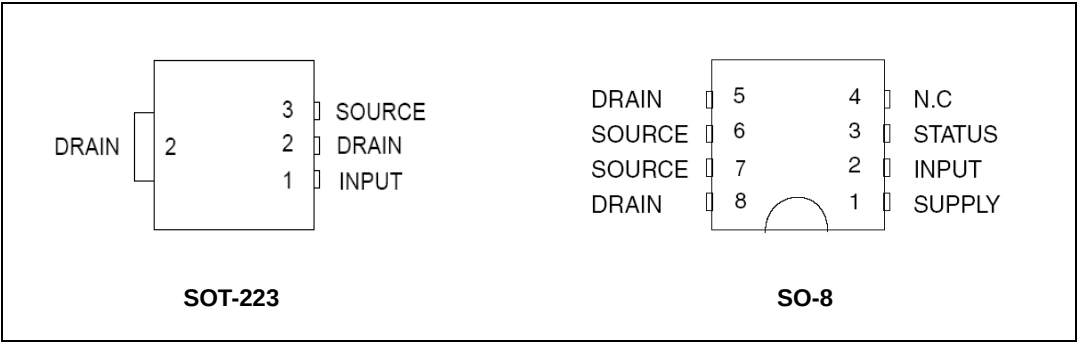


Table 3. Suggested connections for unused and not connected pins

Connection/pin	Status	N.C.	Input
Floating	X	X	X
To ground	Not allowed	X	Through 10kΩ resistor

2 Absolute maximum rating

Stressing the device above the rating listed in [Table 4](#) may cause permanent damage to the device. These are stress ratings only and operation of the device at these or any other conditions above those indicated in the Operating sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

2.1 Absolute maximum ratings

Table 4. Absolute maximum ratings

Symbol	Parameter	Value		Unit
		SOT-223	SO-8	
V _{DS}	Drain-source voltage (V _{IN} =0V)	Internally clamped		V
I _D	DC drain current	Internally limited		A
-I _D	Reverse DC drain current	4		A
I _S	DC supply current	-	-1 to 10	mA
I _{IN}	DC input current	-1 to 10		mA
I _{STAT}	DC status current	-	-1 to 10	mA
V _{ESD1}	Electrostatic discharge (R=1.5kΩ; C=100pF)			V
	– INPUT	4000		
	– STATUS	4000		
	– SUPPLY	4000		
	– DRAIN	5000		
V _{ESD2}	Electrostatic discharge on output pin only (R=330Ω, C=150pF)	2000		V
T _j	Junction operating temperature	-40 to 150		°C
T _{stg}	Storage temperature	-55 to 150		°C
E _{as}	Single pulse avalanche energy L = 8.5 mH, T _j = 150 °C, R _L = 0 Ω, V _{batt} = 13.5 V, I _{out} = I _{limL}	37		mJ

2.2 Thermal data

Table 5. Thermal data

Symbol	Parameter	Maximum value		Unit
		SOT-223	SO-8	
$R_{thj-amb}$	Thermal resistance junction-ambient	146.8 ⁽¹⁾	103.1	°C/W

1. When mounted on a standard single-sided FR4 board with 0.5cm² of Cu (at least 35 µm thick) connected to all DRAIN pins

3 Electrical characteristics

Values specified in this section are for $V_{IN} = V_{supply} = 4.5\text{ V to }5.5\text{ V}$, $-40\text{ °C} < T_j < 150\text{ °C}$, unless otherwise stated.

Table 6. PowerMOS section

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
V_{supply}	Operating supply voltage		3.5	5	5.5	V
R_{ON}	On-state resistance	$V_{IN} = V_{supply} = 5\text{ V}; I_D = 1\text{ A}; T_j = 25\text{ °C}$		160	170	mΩ
		$V_{IN} = V_{supply} = 5\text{ V}; I_D = 1\text{ A}; T_j = 150\text{ °C}$			320	mΩ
V_{CLAMP}	Drain-source clamp voltage	$V_{IN} = 0\text{ V}; I_D = 1\text{ A}$	41	46	52	V
V_{CLTH}	Drain-source clamp threshold voltage	$V_{IN} = 0\text{ V}; I_D = 2\text{ mA}$	36			V
I_{DSS}	Off-state output current	$V_{IN} = 0\text{ V}; V_{DS} = 13\text{ V}; T_j = 25\text{ °C}$	0		3	μA
		$V_{IN} = 0\text{ V}; V_{DS} = 13\text{ V}; T_j = 125\text{ °C}$	0		5	μA

Table 7. Source drain diode

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
V_{SD}	Forward on voltage	$I_D = 1\text{ A}; V_{IN} = 0\text{ V}$	—	0.8	—	V

Table 8. Input section⁽¹⁾

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
I_{ISS}	Supply current from input pin	On-state $V_{IN} = V_{supply} = 5\text{ V}; V_{DS} = 0\text{ V}$		30	65	μA
V_{ICL}	Input clamp voltage	$I_S = 1\text{ mA}$	5.5		7	V
		$I_S = -1\text{ mA}$		-0.7		V
V_{INTH}	Input threshold voltage	$V_{DS} = V_{IN}; I_D = 1\text{ mA}$	1		3.5	V

1. Valid for VNL5160N3-E option (input & supply pins connected together).

Table 9. Status pin⁽¹⁾

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
V_{STAT}	Status low output voltage	$I_{STAT} = 1\text{ mA}$			0.5	V
I_{LSTAT}	Status leakage current	Normal operation, $V_{STAT} = 5\text{ V}$			10	μA

Table 9. Status pin⁽¹⁾ (continued)

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
C_{STAT}	Status pin input capacitance	Normal operation; $V_{STAT} = 5\text{ V}$			100	pF
V_{STCL}	Status clamp voltage	$I_{STAT} = 1\text{ mA}$	5.5		7	V
		$I_{STAT} = -1\text{ mA}$		-0.7		V

1. Valid for VNL5160S5-E option.

Table 10. Logic input⁽¹⁾

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
V_{IL}	Input low level voltage				0.9	V
I_{IL}	Low level input current	$V_{IN} = 0.9\text{ V}$	1			μA
V_{IH}	Input high level voltage		2.1			V
I_{IH}	High level input current	$V_{IN} = 2.1\text{ V}$			10	μA
$V_{I(hyst)}$	Input hysteresis voltage		0.13			V
V_{ICL}	Input clamp voltage	$I_{IN} = 1\text{ mA}$	5.5		7	V
		$I_{IN} = -1\text{ mA}$		-0.7		V

1. Valid for VNL5160S5-E option.

Table 11. Open-load detection⁽¹⁾

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
V_{OI}	Open-load off-state voltage detection threshold	$V_{IN} = 0\text{ V}$	0.6	1.2	1.7	V
$t_{d(oloff)}$	Delay between INPUT falling edge and STATUS falling edge in open-load condition	$I_{OUT} = 0\text{ A}$	45	425	1100	μs

1. Valid for VNL5160S5-E option.

Table 12. Supply section⁽¹⁾

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
I_S	Supply current	Off-state $T_j = 25\text{ }^\circ\text{C}$; $V_{IN} = V_{DRAIN} = 0\text{ V}$		10	25	μA
		On-state $T_j = 25\text{ }^\circ\text{C}$; $V_{IN} = 5\text{ V}$; $V_{DS} = 0\text{ V}$		25	65	μA
V_{SCL}	Supply clamp voltage	$I_{SCL} = 1\text{ mA}$	5.5		7	V
		$I_{SCL} = -1\text{ mA}$		-0.7		V

1. Valid for VNL5160S5-E option.

Table 13. Switching characteristics ($V_{CC} = 13\text{ V}^{(1)}$)

Symbol	Parameter	Test conditions	SOT-223 ⁽²⁾			SO-8			Unit
			Min.	Typ.	Max	Min.	Typ.	Max.	
$t_{d(ON)}$	Turn-on delay time	$R_L = 13\Omega$, $V_{CC} = 13\text{V}^{(3)}$		8.9			8.9		μs
$t_{d(OFF)}$	Turn-off delay time	$R_L = 13\Omega$, $V_{CC} = 13\text{V}$		13.2			13.2		μs
t_r	Rise time	$R_L = 13\Omega$, $V_{CC} = 13\text{V}$		14.1			14.1		μs
t_f	Fall time	$R_L = 13\Omega$, $V_{CC} = 13\text{V}$		11.5			11.5		μs
W_{ON}	Switching energy losses at turn-on	$R_L = 13\Omega$, $V_{CC} = 13\text{V}$		34.3			34.3		μJ
W_{OFF}	Switching energy losses at turn-off	$R_L = 13\Omega$, $V_{CC} = 13\text{V}$		34.3			34.3		μJ

1. See [Figure 7: VNL5160N3-E application schematic](#) and [Figure 8: VNL5160S5-E application schematic](#).

2. $3.5\text{ V} < V_{S_{supply}} = V_{in} < 5.5\text{ V}$.

3. See [Figure 6: Switching characteristics](#).

Table 14. Protection and diagnostics

Symbol	Parameter	Test conditions ⁽¹⁾	Min.	Typ.	Max.	Unit
I_{limH}	DC short circuit current	$V_{DS} = 13\text{V}$; $V_{IN} = V_{supply} = 5\text{V}$	3.5	5	7.5	A
I_{limL}	Short circuit current during thermal cycling	$V_{DS} = 13\text{V}$; $T_R < T_J < T_{TSD}$; $V_{IN} = V_{supply} = 5\text{V}$		2.5		A
t_{dlim}	Step response current limit	$V_{DS} = 13\text{V}$; $V_{input} = 5\text{V}$		20		μs
T_{TSD}	Shutdown temperature		150	175	200	$^{\circ}\text{C}$
T_R	Reset temperature		$T_{RS}+1$	$T_{RS}+5$		$^{\circ}\text{C}$
$T_{RS}^{(2)}$	Thermal reset of STATUS		135			$^{\circ}\text{C}$
T_{HYST}	Thermal hysteresis ($T_{TSD} - T_R$)			7		$^{\circ}\text{C}$

1. $V_{supply}=V_{input}$ in VNL5160N3-E version.

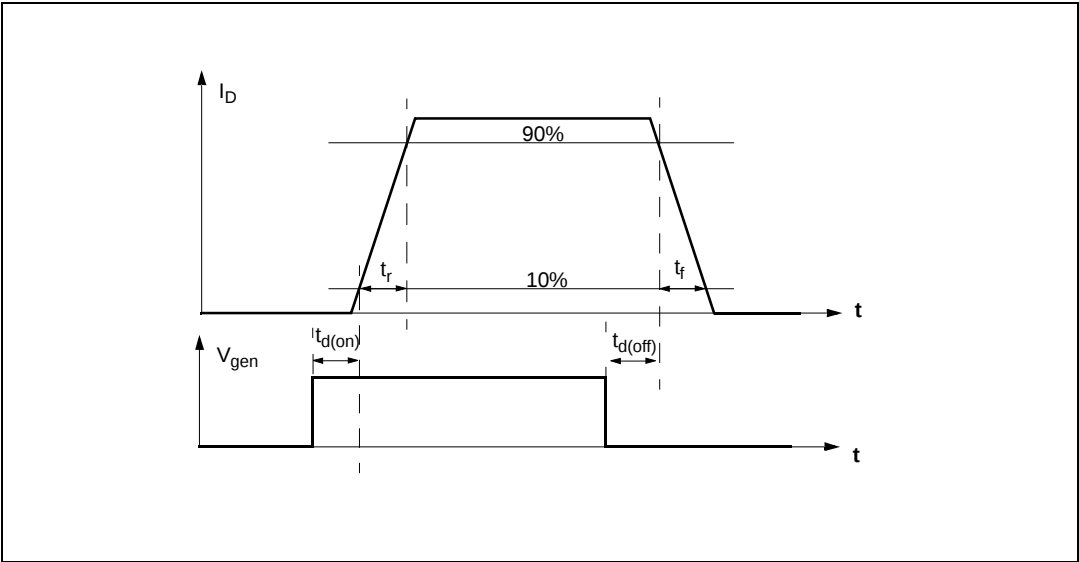
2. Valid for VNL5160S5-E option.

Table 15. Truth table (1)

Conditions	INPUT	DRAIN	STATUS
Normal operation	L	H	H
	H	L	H
Current limitation	L	H	H
	H	X	H
Overtemperature	L	H	H
	H	H	L
Undervoltage	L	H	X
	H	H	X
Output voltage < V _{OL}	L	L	L
	H	L	H

1. Valid for VNL5160S5-E option

Figure 6. Switching characteristics



4 Application information

Figure 7. VNL5160N3-E application schematic

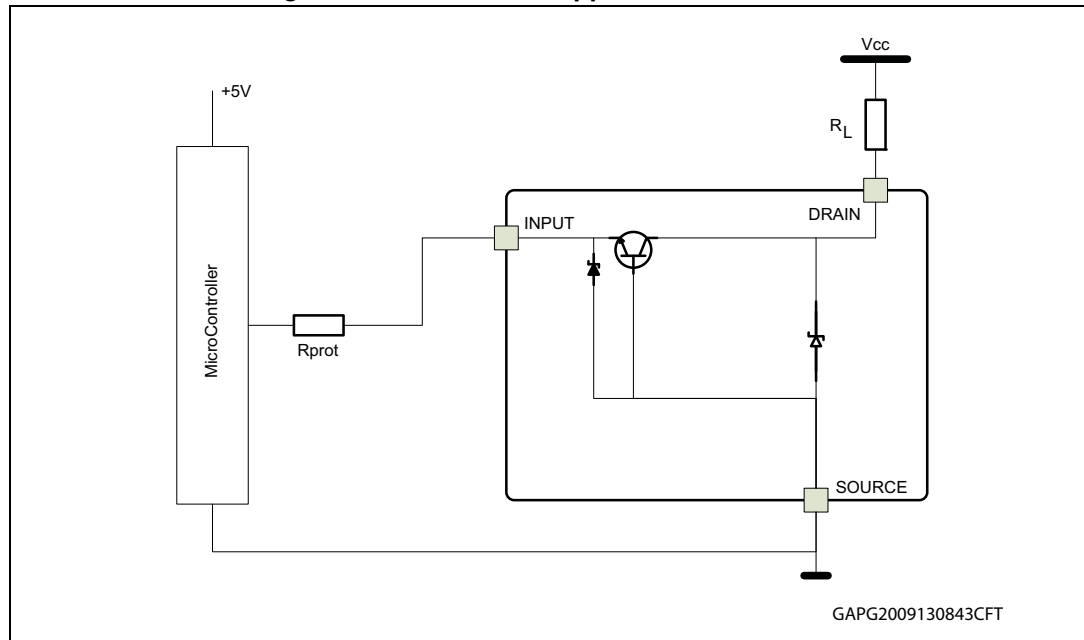
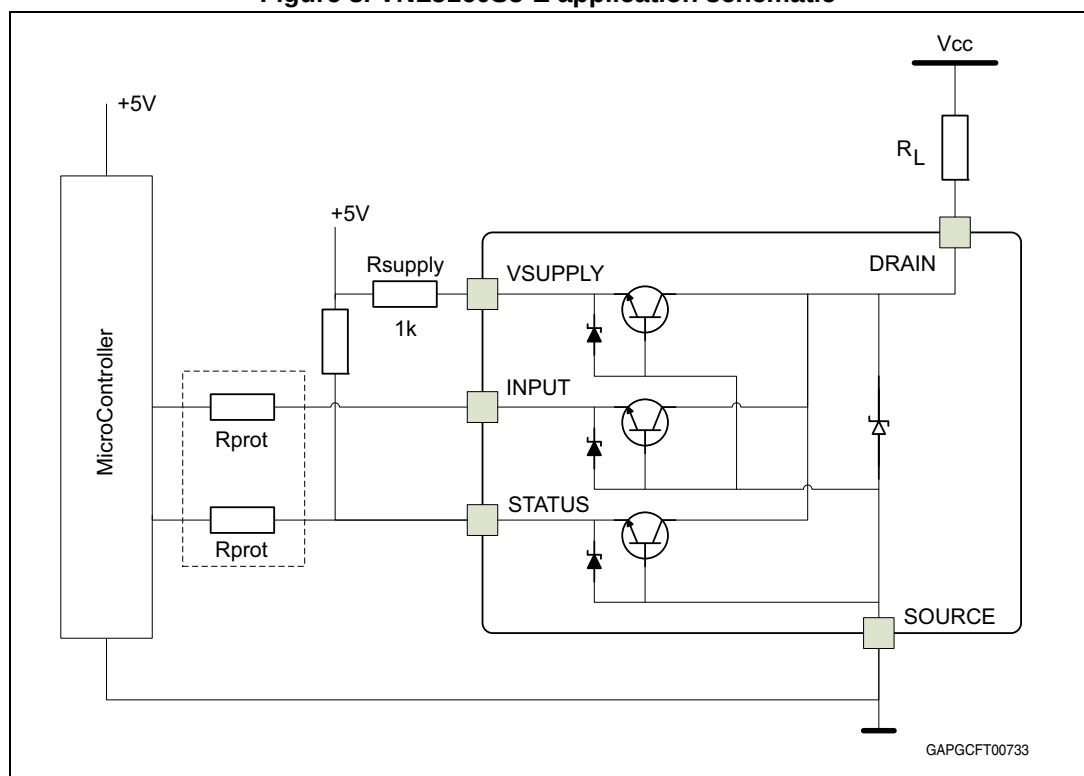


Figure 8. VNL5160S5-E application schematic



4.1 MCU I/O protection

ST suggests to insert a resistor (R_{prot}) in line to prevent the μC I/O pins from latching up^(a). The value of these resistors is a compromise between the leakage current of μC and the current required by the LSD I/Os (Input levels compatibility) with the latch-up limit of μC I/Os:

$$0.7/I_{latchup} \leq R_{prot} \leq (V_{OH\mu C} - V_{IH}) / I_{IHmax}$$

Calculation example:

For the following conditions:

$$I_{latchup} \geq 20mA$$

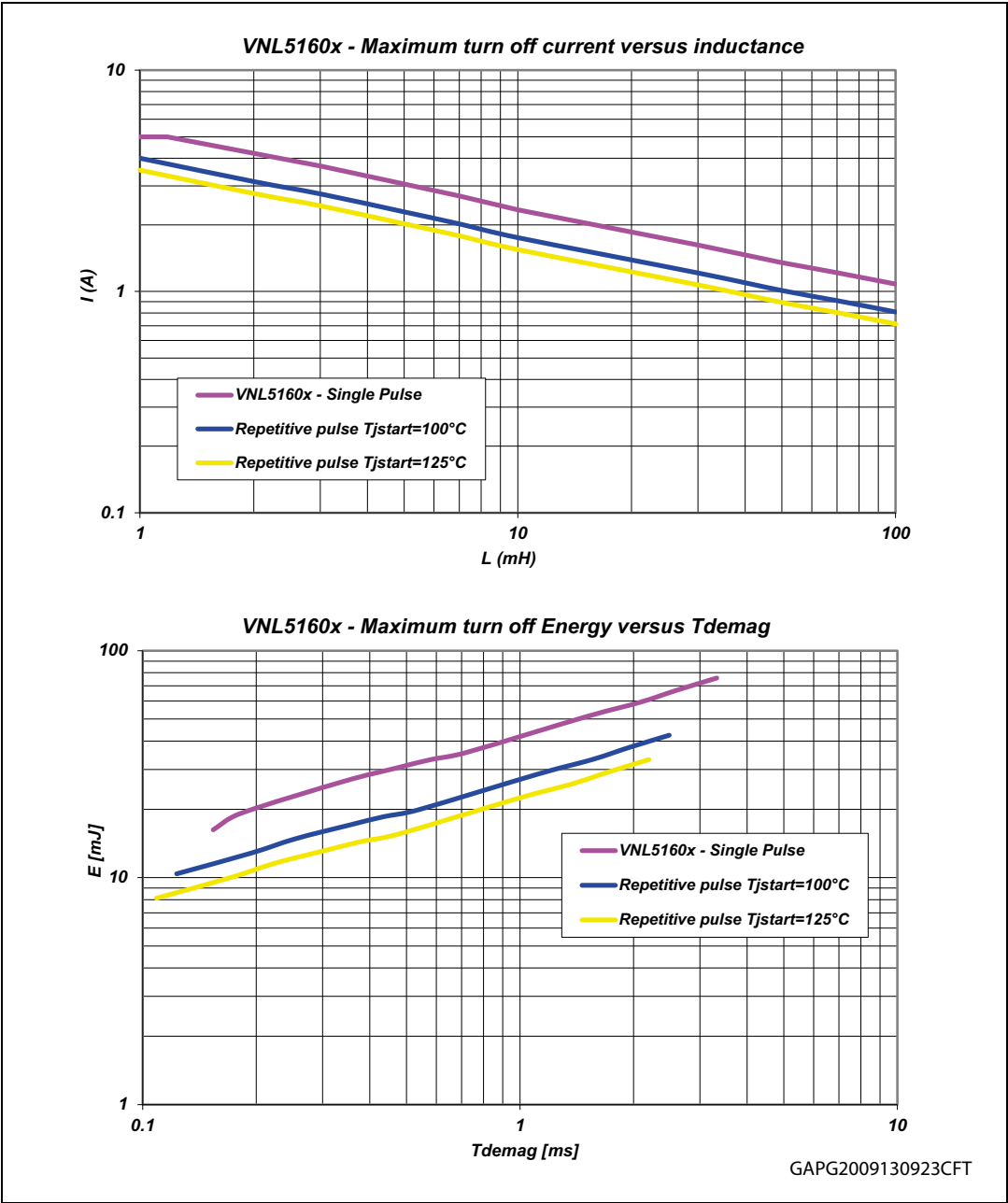
$$V_{OH\mu C} \geq 4.5V$$

$$35\Omega \leq R_{prot} \leq 100k\Omega.$$

Recommended value is $R_{prot} = 1 k\Omega$

a. In case of negative transient on the drain pin.

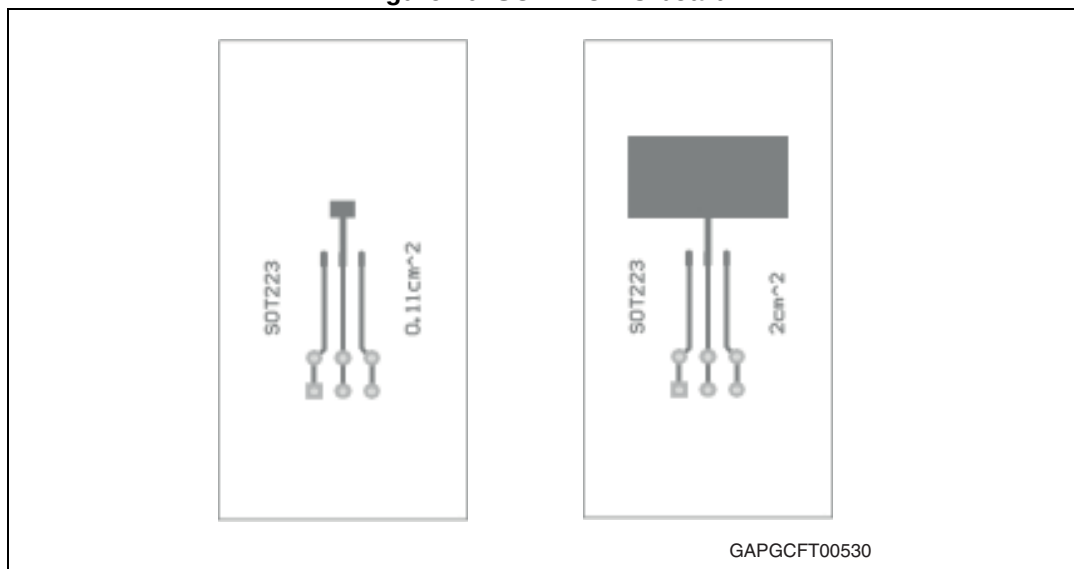
Figure 9. Maximum demagnetization energy



5 Package and PC board thermal data

5.1 SOT-223 thermal data

Figure 10. SOT-223 PC board



Note: Layout condition of R_{th} and Z_{th} measurements (PCB FR4 area = 30 mm x 30 mm, PCB thickness = 2 mm, Cu thickness = 35 μ m, Copper areas: from minimum pad layout to 0.8 cm²).

Figure 11. SOT-223 $R_{thj-amb}$ vs PCB copper area in open box free air condition

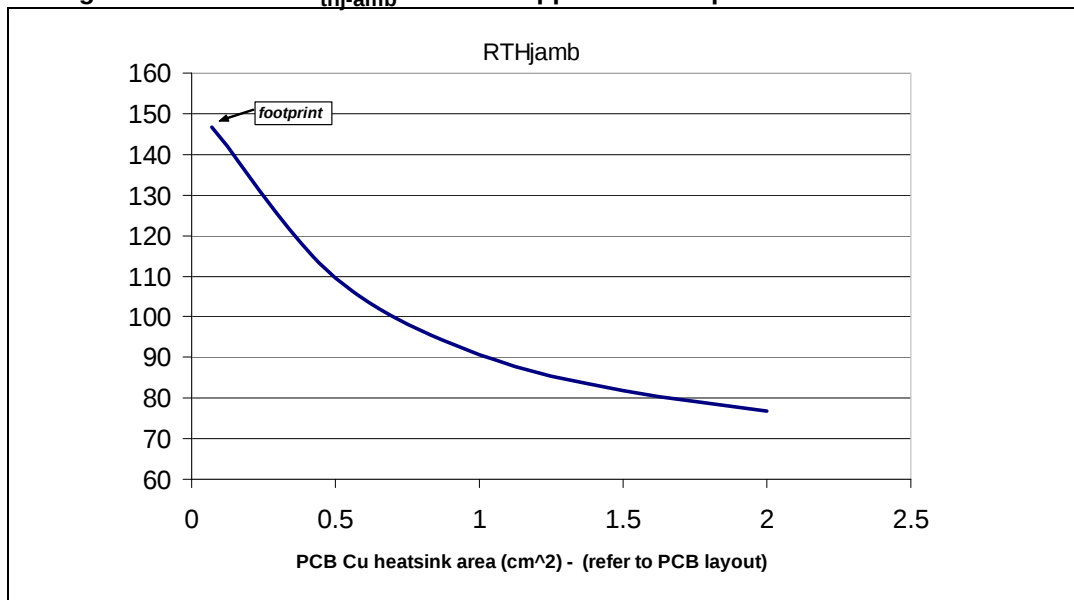
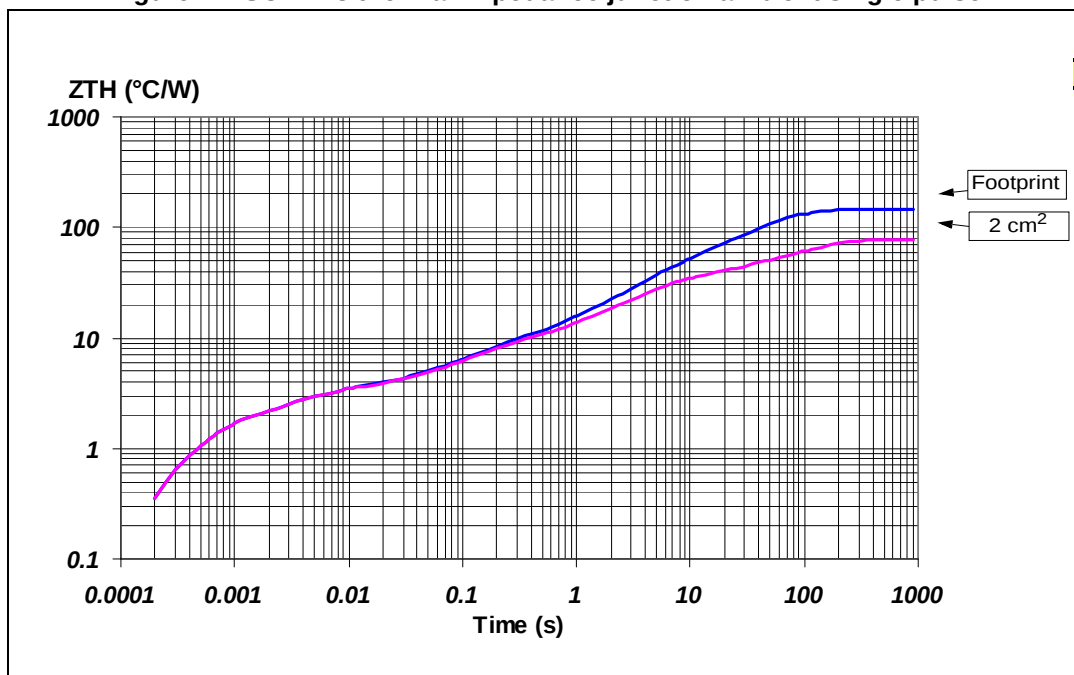


Figure 12. SOT-223 thermal impedance junction ambient single pulse

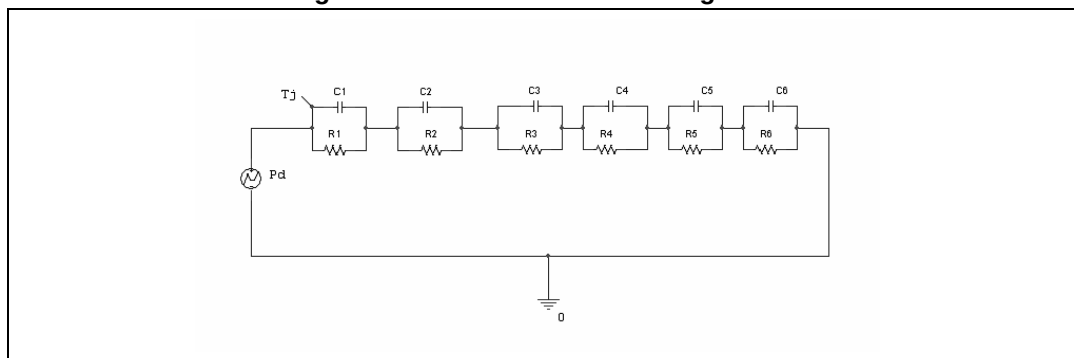


Equation 1: pulse calculation formula

$$Z_{TH\delta} = R_{TH} \cdot \delta + Z_{THtp}(1 - \delta)$$

where $\delta = t_p/T$

Figure 13. SOT-223 thermal fitting model



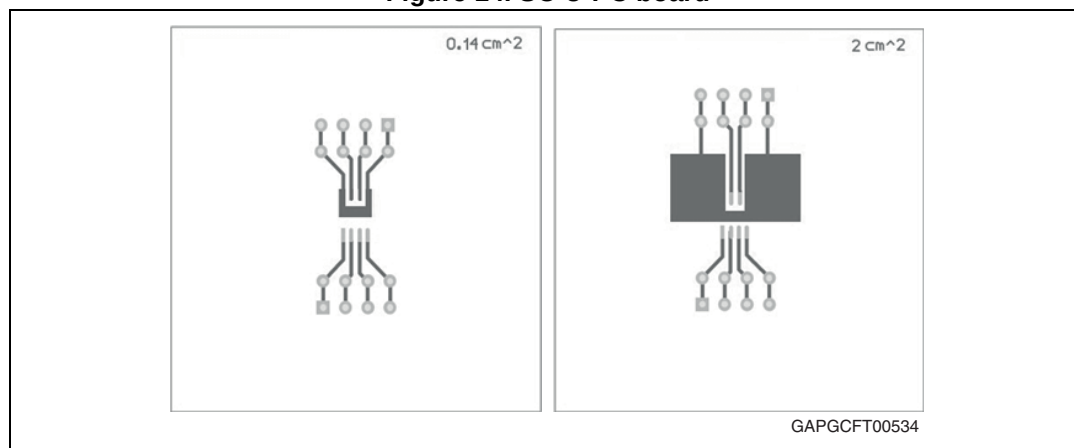
1. The fitting model is a simplified thermal tool and is valid for transient evolutions where the embedded protections (power limitation or thermal cycling during thermal shutdown) are not triggered.

Table 16. SOT-223 thermal parameter

Area/island (cm ²)	FP	2
R1 (°C/W)	1.4	
R2 (°C/W)	1.8	
R3 (°C/W)	4.5	
R4 (°C/W)	24	
R5 (°C/W)	0.1	
R6 (°C/W)	115	45
C1 (W·s/°C)	0.0003	
C2 (W·s/°C)	0.002	
C3 (W·s/°C)	0.03	
C4 (W·s/°C)	0.16	
C5 (W·s/°C)	1000	
C6 (W·s/°C)	0.4	2

5.2 SO-8 thermal data

Figure 14. SO-8 PC board



Note: Layout condition of R_{th} and Z_{th} measurements (PCB FR4 area = 58 mm x 58 mm, PCB thickness = 2 mm, Cu thickness = 35 μ m, Copper areas: from minimum pad layout to 2 cm²).

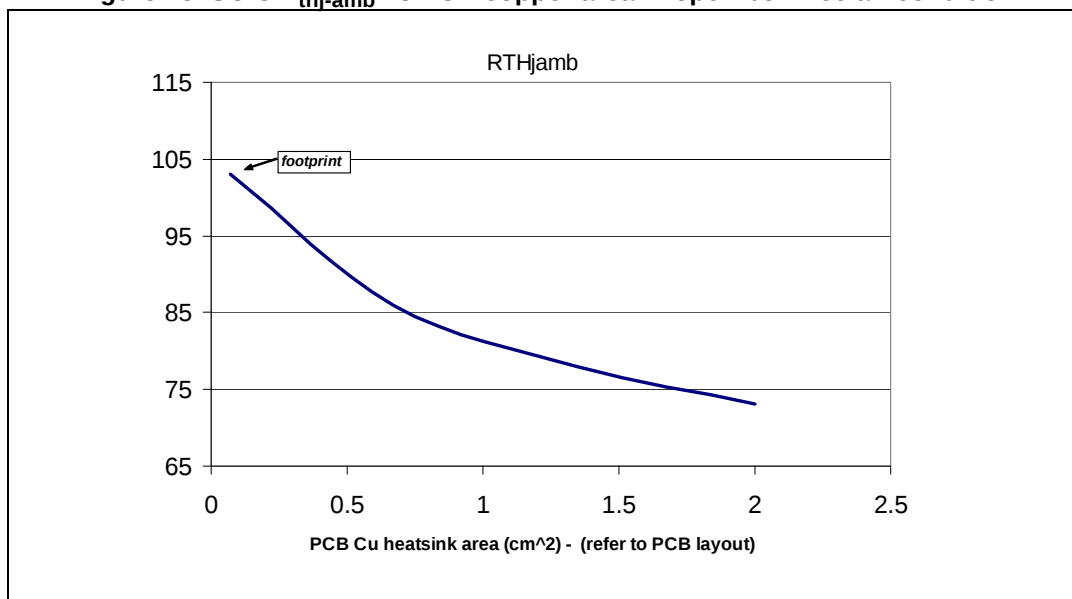
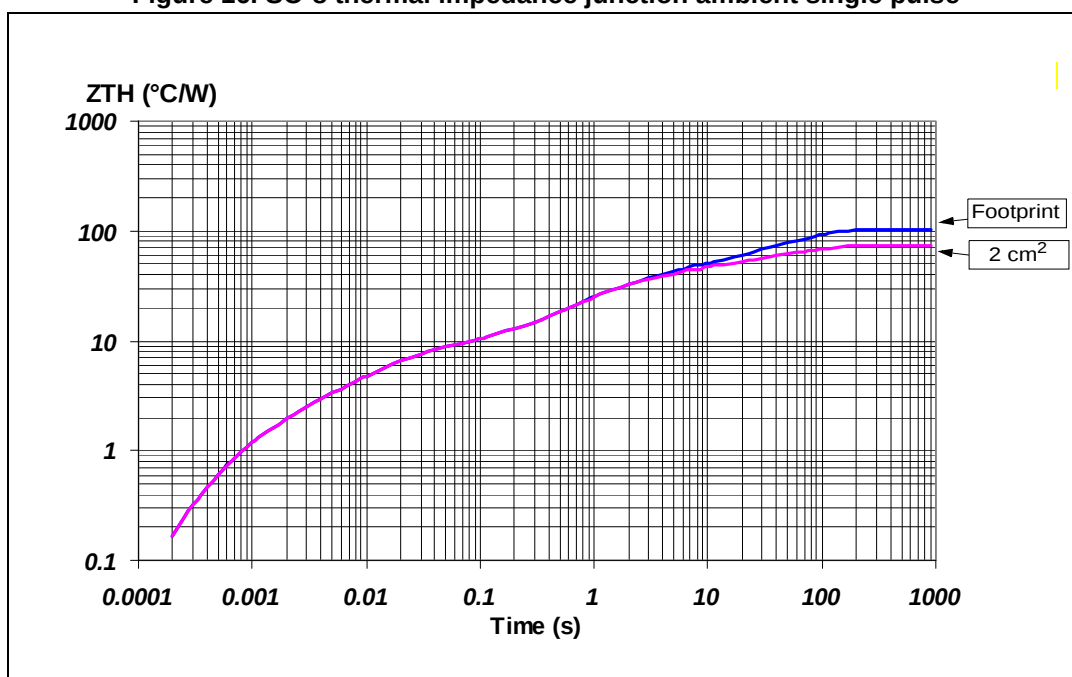
Figure 15. SO-8 $R_{thj-amb}$ vs PCB copper area in open box free air condition

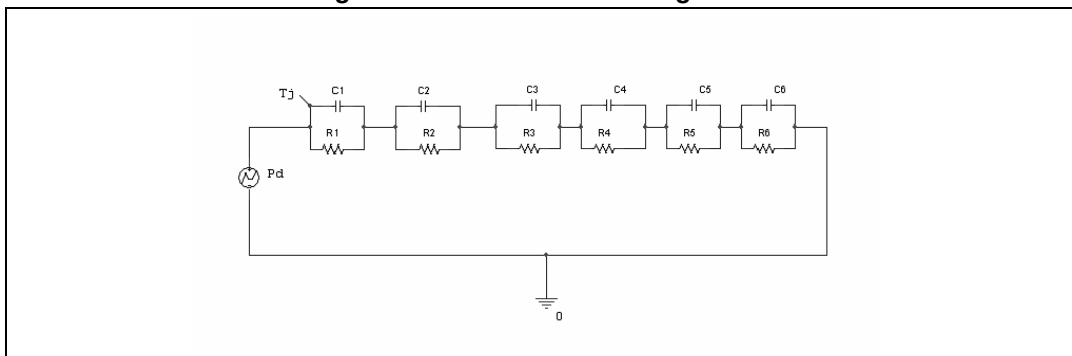
Figure 16. SO-8 thermal impedance junction ambient single pulse

**Equation 2: pulse calculation formula**

$$Z_{TH\delta} = R_{TH} \cdot \delta + Z_{THtp}(1 - \delta)$$

where $\delta = t_p/T$

Figure 17. SO-8 thermal fitting model



1. The fitting model is a simplified thermal tool and is valid for transient evolutions where the embedded protections (power limitation or thermal cycling during thermal shutdown) are not triggered.

Table 17. SO-8 thermal parameter

Arealisland (cm ²)	0.07	2
R1 (°C/W)	1.4	
R2 (°C/W)	3.2	
R3 (°C/W)	3.5	
R4 (°C/W)	21	
R5 (°C/W)	16	
R6 (°C/W)	58	28
C1 (W·s/°C)	0.0008	
C2 (W·s/°C)	0.0032	
C3 (W·s/°C)	0.0075	
C4 (W·s/°C)	0.045	
C5 (W·s/°C)	0.35	
C6 (W·s/°C)	1.05	2

6 Package and packing information

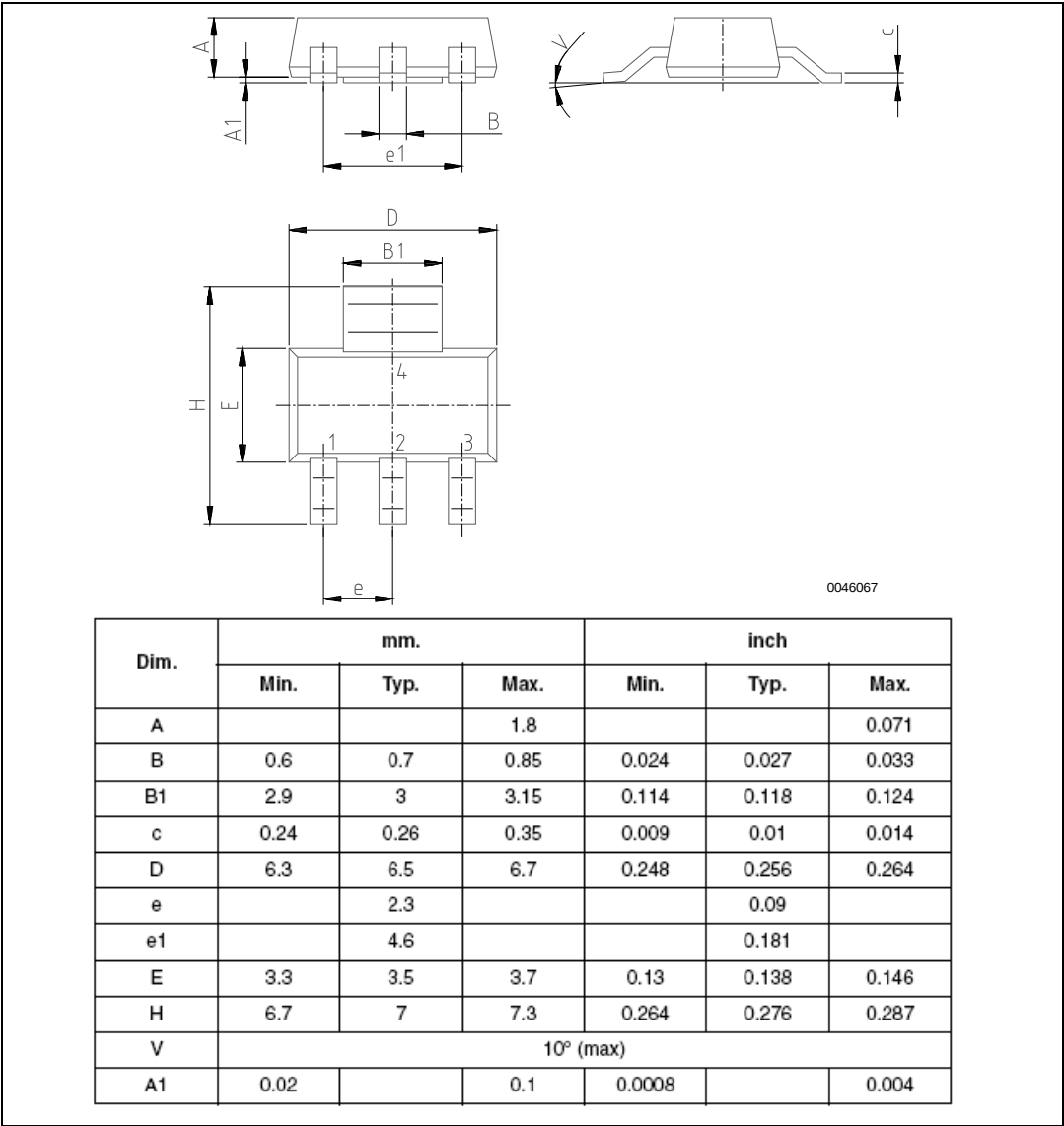
6.1 ECOPACK® packages

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: www.st.com.

ECOPACK® is an ST trademark.

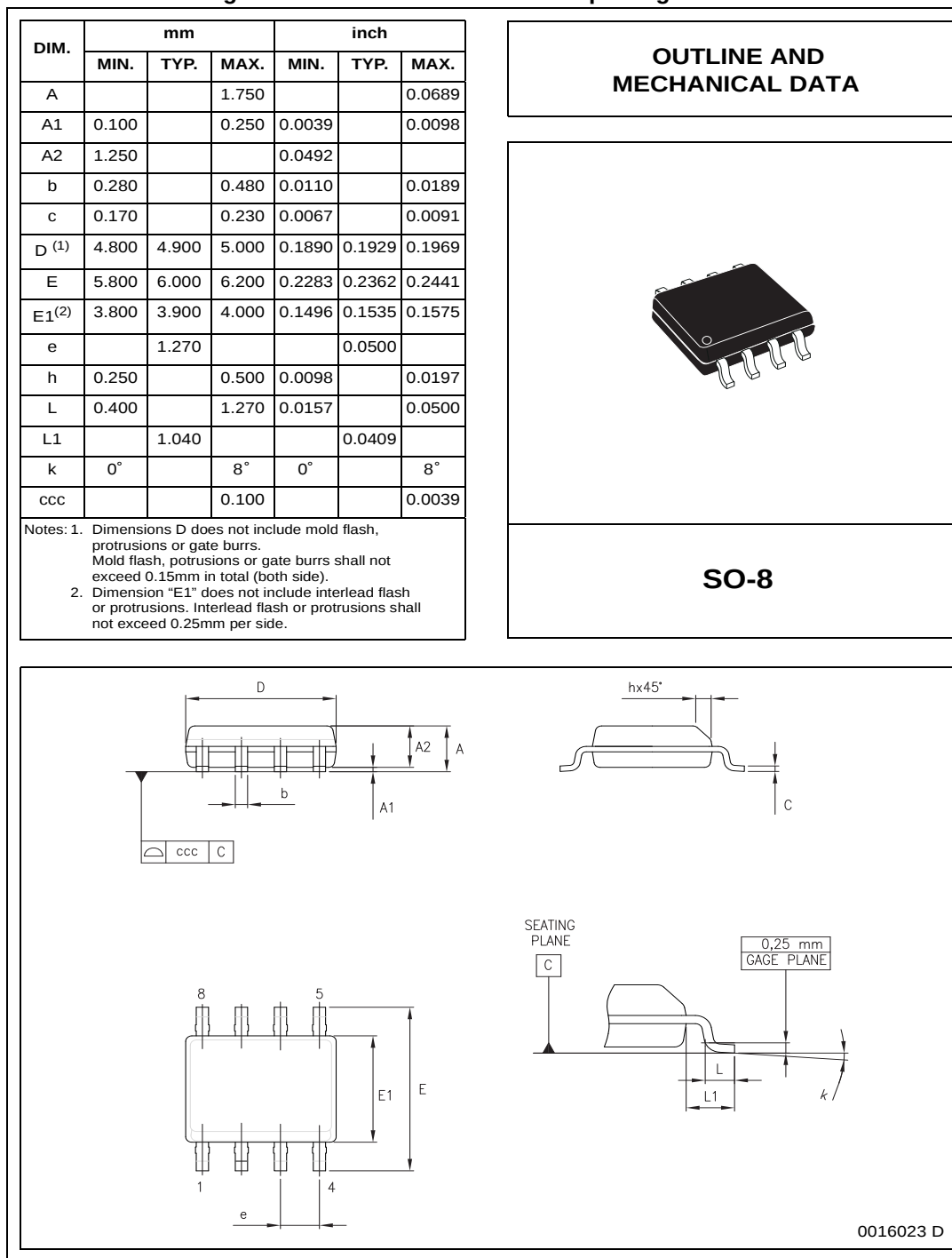
6.2 SOT-223 mechanical data

Figure 18. SOT-223 mechanical data & package outline



6.3 SO8 mechanical data

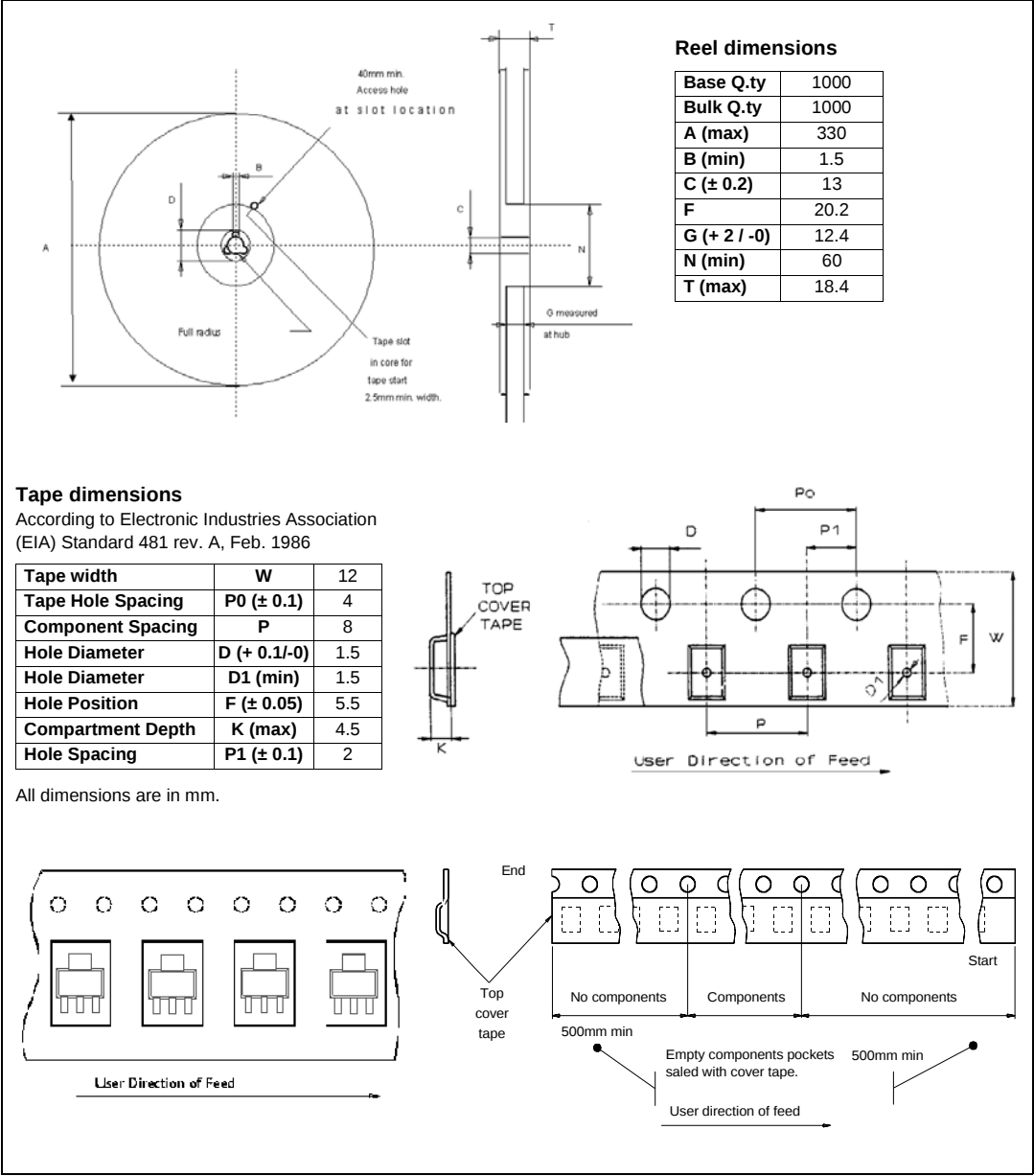
Figure 19. SO8 mechanical data & package outline



6.4 SOT-223 packing information

The devices can be packed in tube or tape and reel shipments (see the [Table 1: Device summary](#)).

Figure 20. SOT-223 tape and reel shipment (suffix “TR”)



6.5 SO8 packing information

Figure 21. SO-8 tube shipment (no suffix)

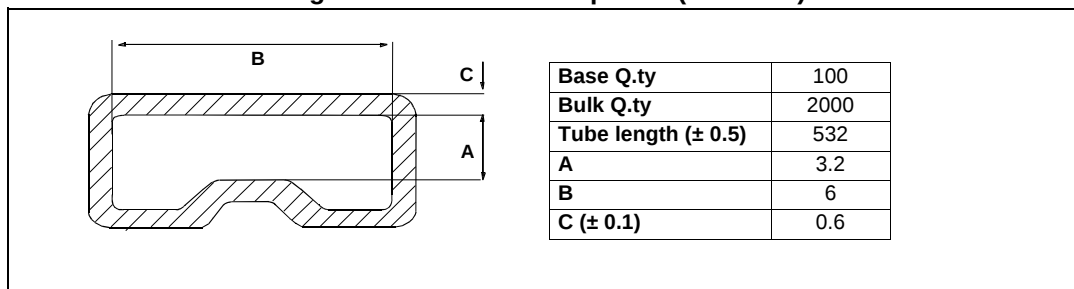
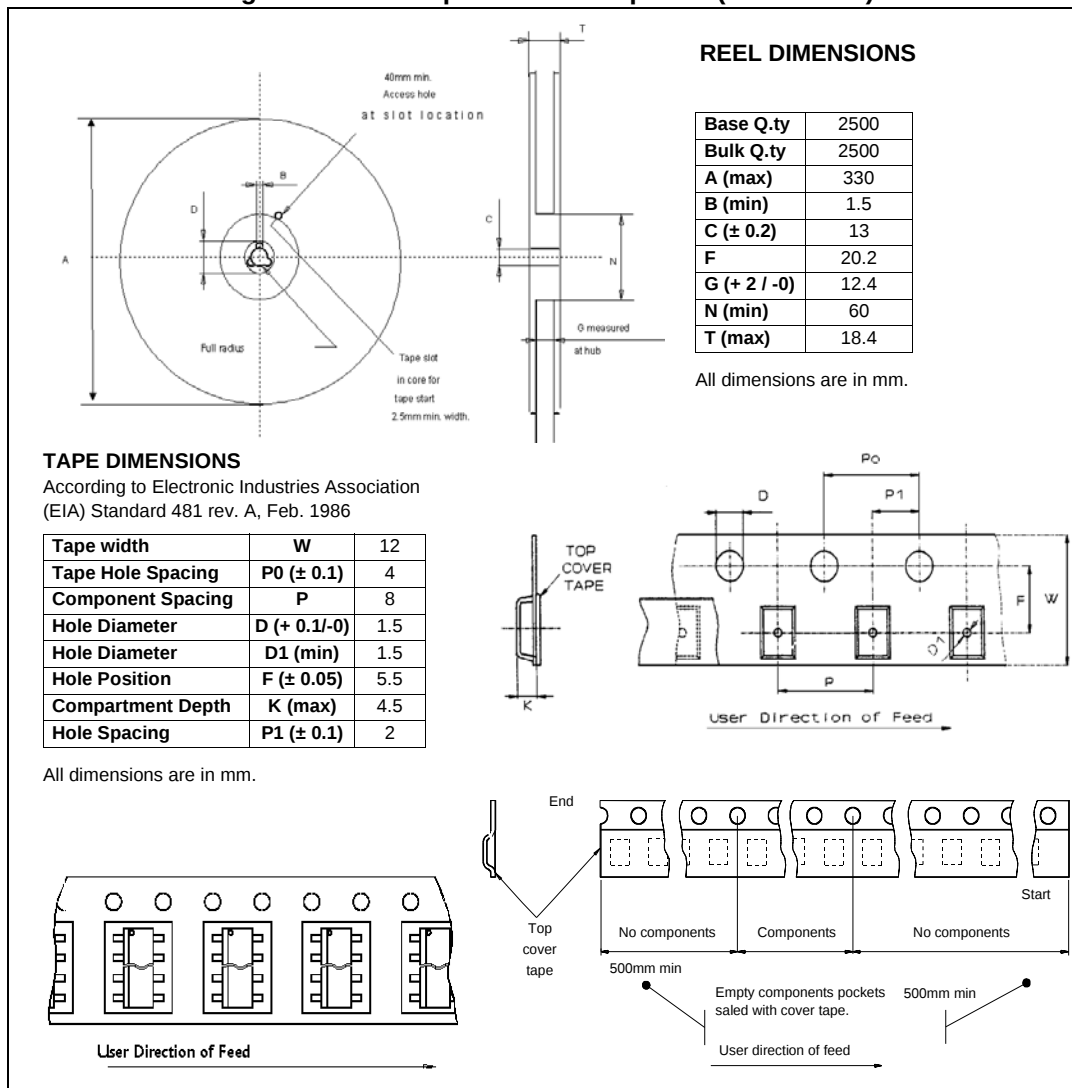


Figure 22. SO-8 tape and reel shipment (suffix "TR")



7 Revision history

Table 18. Document revision history

Date	Revision	Changes
17-Nov-2009	1	Initial release.
20-Feb-2012	2	Update the entire document in ST template. Update Section : Features in cover page.
20-Sep-2013	3	Table 9: Status pin : – I_D : updated value Table 9: Status pin : – I_{SS} : updated max value Table 13: Switching characteristics ($V_{CC} = 13\text{ V}$) : – I_S : updated max value Updated Figure 8: VNL5160S5-E application schematic Updated Section 4.1: MCU I/O protection Updated Figure 9: Maximum demagnetization energy

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